Aluminum Capacitors
SMD (Chip) Standard

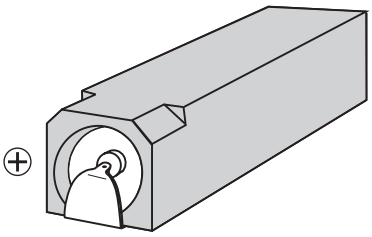
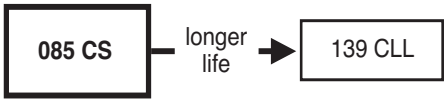


Fig.1 Component outlines



FEATURES

- Polarized aluminum electrolytic capacitors, non-solid electrolyte, self healing
- SMD-version, rectangular case, insulated
- Miniaturized, high CV per unit volume, low height
- Flexible terminals, reflow and wave solderable
- Charge and discharge proof
- Supplied in blister tape on reel.

APPLICATIONS

- SMD technology, boards with restricted mounting height
- General applications, consumer electronics, low profile and lightweight equipment
- Decoupling, smoothing, filtering and buffering.

MARKING

The capacitors are marked (where possible) with the following information:

- Rated capacitance (in µF).
- Rated voltage code (see Table 1), the U_R code letter indicates the position of the decimal point in the capacitance value.
- Name of manufacturer.
- '-' sign indicating the cathode. The anode is identified by bevelled edges.

Examples for C_R; U_R marking:

H22 represents 0.22µF; 63 V

2G2 represents 2.2 µF; 40 V

22C represents 22 µF; 6.3 V.

Table 1

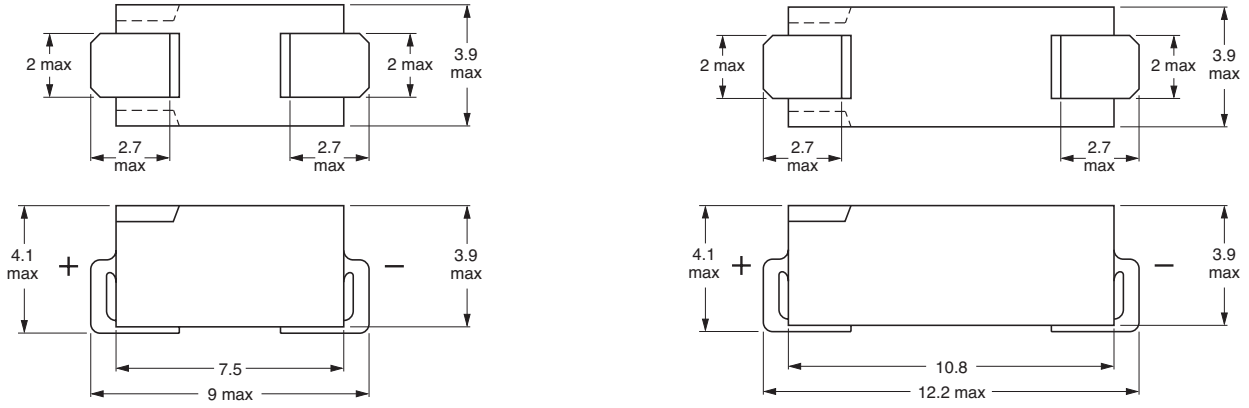
RATED VOLTAGE MARKING CODE						
U_R (V)	6.3	10	16	25	40	63
Code letter	C	D	E	F	G	H

QUICK REFERENCE DATA	
DESCRIPTION	VALUE
Nominal case sizes (L × W × H in mm)	8.8 × 3.7 × 3.9 and 11.9 × 3.7 × 3.9
Rated capacitance range, C_R	0.47 to 22 µF
Tolerance on C_R	10 to +50% or ±20%
Rated voltage range, U_R	6.3 to 63 V
Category temperature range	40 to +85°C
Endurance test at 85 °C	1000 hours
Useful life at 85 °C	1500 hours
Useful life at 40 °C; 1.4 × I_R applied	40000 hours
Shelf life at 0 V, 85 °C	500 hours
Resistance to soldering heat test	immersion in solder: 10 s at 260 °C or 20 s at 215 °C
Based on sectional specification	IEC 60384-18/CECC 32300
Climatic category IEC 60068	40/085/56

SELECTION CHART FOR C_R, U_R AND RELEVANT NOMINAL CASE SIZES (L x W x H in mm)

C_R (µF)	U_R (V)					
	6.3	10	16	25	40	63
0.47	-	-	-	-	-	8.8 × 3.7 × 3.9
1.0	-	-	-	-	-	8.8 × 3.7 × 3.9
2.2	-	-	-	-	8.8 × 3.7 × 3.9	11.9 × 3.7 × 3.9
3.3	-	-	-	8.8 × 3.7 × 3.9	-	11.9 × 3.7 × 3.9
4.7	-	-	8.8 × 3.7 × 3.9	-	11.9 × 3.7 × 3.9	-
6.8	-	8.8 × 3.7 × 3.9	-	11.9 × 3.7 × 3.9	-	-
10	8.8 × 3.7 × 3.9	-	11.9 × 3.7 × 3.9	-	-	-
15	-	11.9 × 3.7 × 3.9	-	-	-	-
22	11.9 × 3.7 × 3.9	-	-	-	-	-

DIMENSIONS in millimeters



a. Case size 8.8 × 3.7 × 3.9 mm.

b. Case size 11.9 x 3.7 x 3.9 mm.

Fig.2 Dimensional outlines.

PACKAGING

Tape on reel packaging: 2000 per reel.

Detailed tape dimensions see section 'PACKAGING'.

MOUNTING

The capacitors are designed for automatic placement on printed-circuit boards or hybrid circuits.

Optimum dimensions of soldering pads depend upon soldering method, mounting accuracy, print lay-out and/or adjacent components.

For recommended pad dimensions, refer to Fig. 3 and Table 2.

Table 2

RECOMMENDED SOLDERING PAD DIMENSIONS in millimeters (placement accuracy ±0.25mm)														
NOMINAL CASE SIZE L × W × H	**FOR REFLOW SOLDERING**							**FOR WAVE SOLDERING**						
	A	**B**	**C**	**D**	**E**	**F**	**G**	**A**	**B**	**C**	**D**	**E**	**F**	**G**
8.8 × 3.7 × 3.9	9.7	3.5	2.9	2.5	3.0	10.1	4.4	13.5	4.1	4.7	3.7	2.9	14.0	8.4
11.9 × 3.7 × 3.9	12.9	6.5	2.9	2.5	6.0	13.3	4.4	16.8	7.4	4.7	3.7	6.1	17.3	8.4

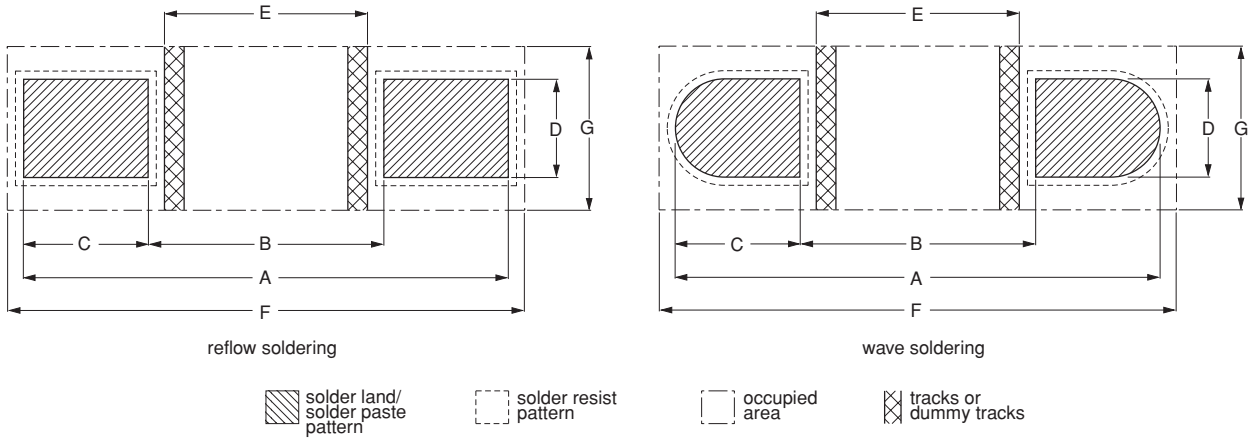
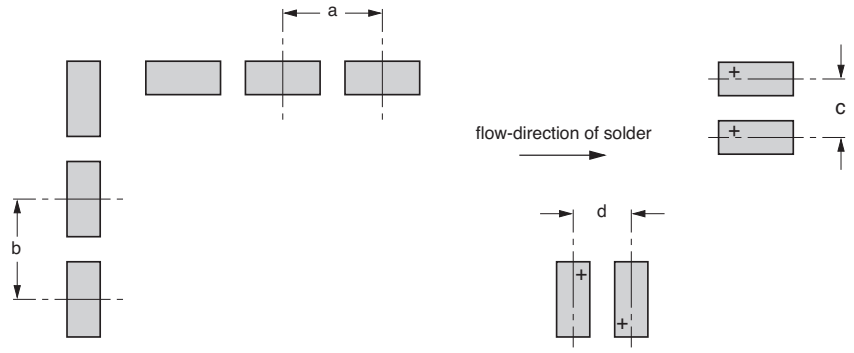


Fig.3 Recommended pad dimensions for reflow and wave soldering.



For dimensions a, b, c and d, refer to Table 3 .
Flow direction of solder preferably onto side-walls or plus-side of the capacitors.

Fig.4 Minimum distances between 085 CS capacitors on a printed-circuit board for wave soldering.

SOLDERING

Soldering conditions are defined by the curve, temperature versus time. The temperature is that measured on the soldering pad during processing.

For maximum conditions of different soldering methods see Figs 5, 6 and 7.

Any temperature/time curve which does not exceed the specified maximum curves may be applied.

AS A GENERAL PRINCIPLE, TEMPERATURE AND DURATION SHALL BE THE **MINIMUM** NECESSARY REQUIRED TO ENSURE GOOD SOLDERING CONNECTIONS.

Table 3

MINIMUM DISTANCES BETWEEN CAPACITORS in millimeters					
NOMINAL CASE SIZE L × W × H	**CASE CODE**	**a_{min}**	**b_{min}**	**c_{min}**	**d_{min}**
8.8 × 3.7 × 3.9	1a	12	12	6.8	6.8
11.9 × 3.7 × 3.9	1	15	15	6.8	6.8

Table 4

CURING CONDITIONS FOR SMD-GLUE	
MAX. T_{amb} (°C)	**MAX. EXPOSURE TIME (minutes)**
125	10
140	3
150	1
160	0.5

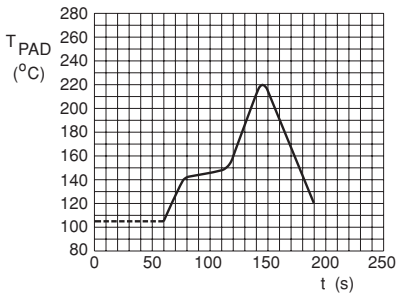


Fig.5 Maximum temperature load during infrared reflow soldering.

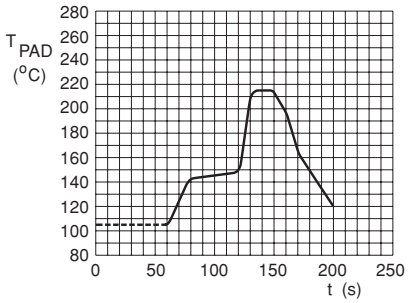


Fig.6 Maximum temperature load during vapour phase reflow soldering.

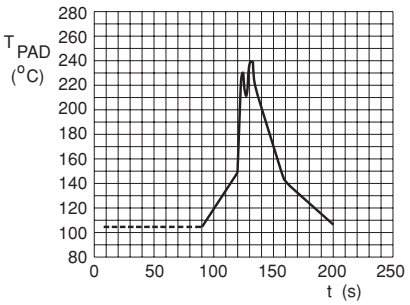


Fig.7 Maximum temperature load during (double-) wave soldering.

ELECTRICAL DATA

SYMBOL	DESCRIPTION
C_R	rated capacitance at 100 Hz (tolerance –10 to +50% or ±20%)
I_R	rated RMS ripple current at 100 Hz, 85 °C
I_{L5}	max. leakage current after 5 minutes at U_R
Tan δ	max. dissipation factor at 100 Hz
Z	max. impedance at 10 kHz

Note

1. Unless otherwise specified, all electrical values in Table 5 apply at T_{amb} = 20 °C, P = 86 to 106 kPa, RH = 45 to 75%.

ORDERING EXAMPLE

Electrolytic capacitor 085 series

10 μF/16 V; –10/+50%

Nominal case size: 11.9 × 3.7 × 3.9 mm; Form BR

Catalog number: 2222 085 25109.

Table 5

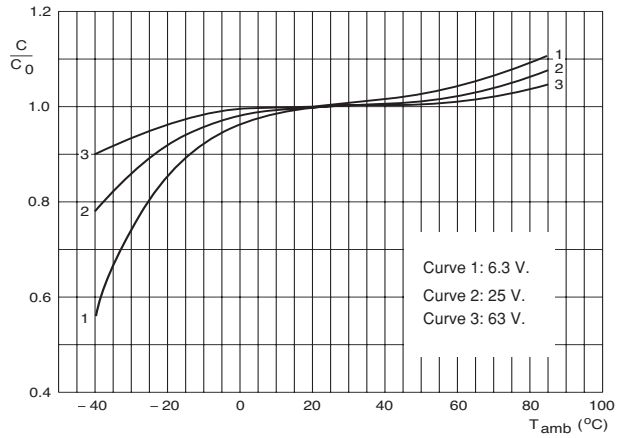
ELECTRICAL DATA AND ORDERING INFORMATION

U_R (V)	C_R 100 Hz (μF)	NOMINAL CASE SIZE L × W × H (mm)	I_R 100 Hz 85 °C (mA)	I_{L5} 5 min (μA)	Tan δ 100 Hz	Z 10 kHz (Ω)	CATALOG NUMBER 2222 085	
							–10/+50%	±20%
							BLISTER TAPE ON REEL FORM BR	BLISTER TAPE ON REEL FORM BR
6.3	10.0	8.8 × 3.7 × 3.9	11	3.1	0.30	20	23109	63109
	22	11.9 × 3.7 × 3.9	20	3.3	0.30	9	23229	63229
10	6.8	8.8 × 3.7 × 3.9	10	3.1	0.25	24	24688	64688
	15	11.9 × 3.7 × 3.9	18	3.3	0.25	11	24159	64159
16	4.7	8.8 × 3.7 × 3.9	9	3.2	0.20	26	25478	65478
	10	11.9 × 3.7 × 3.9	16	3.3	0.20	12	25109	65109
25	3.3	8.8 × 3.7 × 3.9	8	3.2	0.18	27	26338	66338
	6.8	11.9 × 3.7 × 3.9	14	3.3	0.18	13	26688	66688
40	2.2	8.8 × 3.7 × 3.9	7	3.2	0.16	32	27228	67228
	4.7	11.9 × 3.7 × 3.9	13	3.4	0.16	15	27478	67478
63	0.47	8.8 × 3.7 × 3.9	4	3.1	0.10	120	28477	68477
	1.0	8.8 × 3.7 × 3.9	6	3.1	0.12	55	28108	68108
	2.2	11.9 × 3.7 × 3.9	11	3.3	0.14	25	28228	68228
	3.3	11.9 × 3.7 × 3.9	13	3.4	0.14	17	28338	68338

ADDITIONAL ELECTRICAL DATA

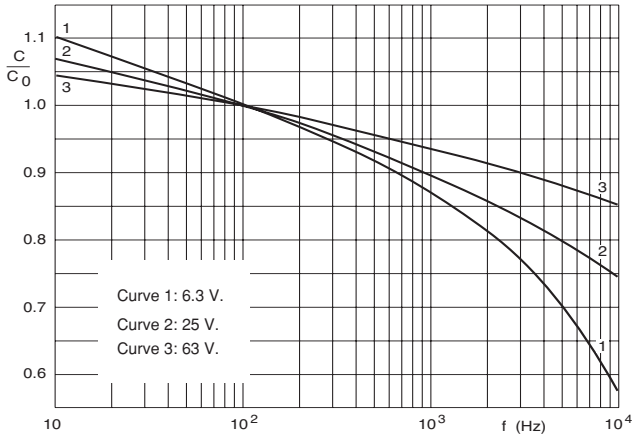
PARAMETER	CONDITIONS	VALUE
Voltage		
Surge voltage for short periods		$U_s \leq 1.15 \times U_R$
Reverse voltage		$U_{rev} \leq 1$ V
Current		
Leakage current	after 1 minute at U_R	$I_{L1} \leq 0.02\ C_R \times U_R + 3$ μA
	after 5 minutes at U_R	$I_{L5} \leq 0.002\ C_R \times U_R + 3$ μA
Inductance		
Equivalent series inductance (ESL)	nominal case size 8.8 × 3.7 × 3.9 mm	typ. 11 nH
	nominal case size 11.9 × 3.7 × 3.9 mm	typ. 13 nH
Resistance		
Equivalent series resistance (ESR)	calculated from tan δ_{max} and C_R (see Table 5)	ESR = tan δ / $2\pi f C_R$

CAPACITANCE (C)



C_0 = capacitance at 20 °C, 100 Hz.

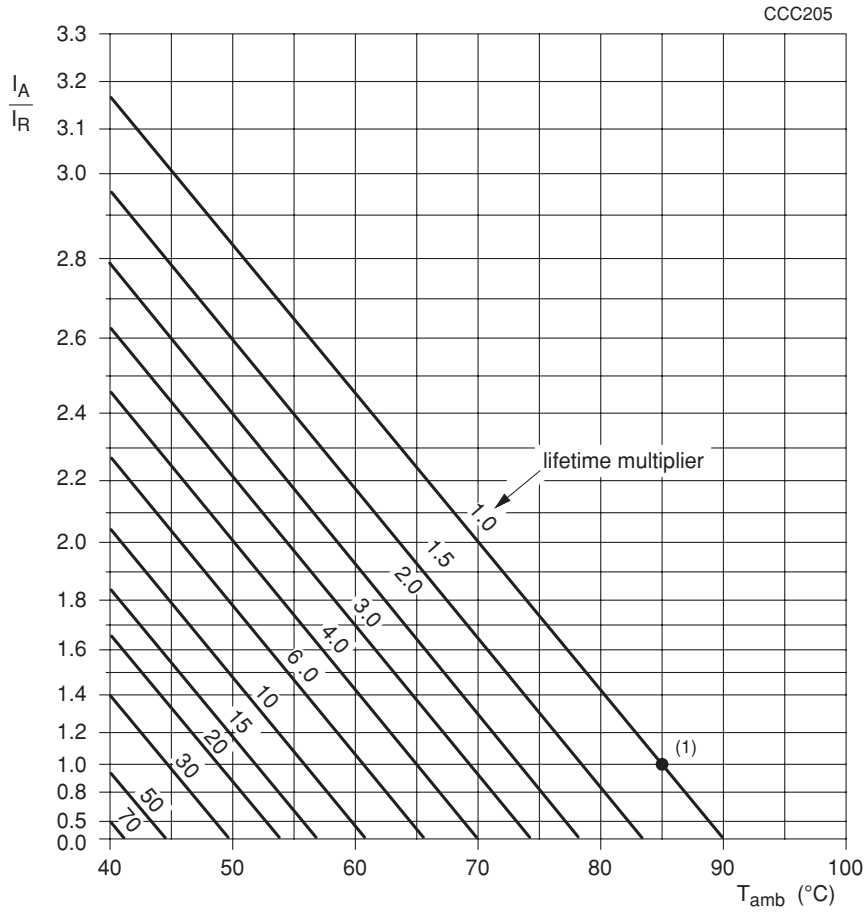
Fig.8 Typical multiplier of capacitance as a function of ambient temperature.



C_0 = capacitance at 20 °C, 100 Hz. T_{amb} = 20 °C.

Fig.9 Typical multiplier of capacitance as a function of frequency.

RIPPLE CURRENT AND USEFUL LIFE



I_A = actual ripple current at 100 Hz.

I_R = rated ripple current at 100 Hz, 85 °C.

(1) Useful life at 85 °C and I_R applied: 1500 hours.

Fig.10 Multiplier of useful life as a function of ambient temperature and ripple current load.

Table 6

MULTIPLIER OF RIPPLE CURRENT (I_R) AS A FUNCTION OF FREQUENCY			
FREQUENCY (Hz)	I_R MULTIPLIER		
	U_R = 6.3 to 16 V	U_R = 25 to 40 V	U_R = 63 V
50	0.80	0.75	0.70
100	1.00	1.00	1.00
300	1.20	1.30	1.55
1000	1.35	1.55	1.90
3000	1.45	1.70	2.30
≥10000	1.50	1.80	2.50

Table 7

TEST PROCEDURES AND REQUIREMENTS			
TEST		PROCEDURE (quick reference)	REQUIREMENTS
NAME OF TEST	REFERENCE		
Mounting	IEC 60384-18, subclause 4.3	shall be performed prior to tests mentioned below; method: reflow or (double-) wave soldering; for maximum temperature load refer to chapter “Mounting”	ΔC/C: ±10% tan δ ≤ spec. limit I_{L5} ≤ 2 × spec. limit
Endurance	IEC 60384-18/ CECC 32300, subclause 4.15	T_{amb} = 85 °C; U_R applied; 1000 hours	ΔC/C: ±20% tan δ ≤ 2 × spec. limit Z ≤ 3 × spec. limit I_{L5} ≤ spec. limit
Useful life	CECC 30301, subclause 1.8.1	T_{amb} = 85 °C; U_R and I_R applied; 1500 hours	ΔC/C: ±50% tan δ ≤ 3 × spec. limit Z ≤ 3 × spec. limit I_{L5} ≤ spec. limit no short or open circuit total failure percentage: ≤ 3%
Shelf life (storage at high temperature)	IEC 60384-18/ CECC 32300, subclause 4.17	T_{amb} = 85 °C; no voltage applied; 500 hours after test: U_R to be applied for 30 minutes, 24 to 48 hours before measurement	ΔC/C, tan δ, Z: for requirements see ‘Endurance test’ above I_{L5} ≤ 2 × spec. limit